![Chipsmall logo]

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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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N-Channel Enhancement-Mode Vertical DMOS FET

Features

- ► Free from secondary breakdown
- ► Low power drive requirement
- ► Ease of paralleling
- ► Low C_{ISS} and fast switching speeds
- ► Excellent thermal stability
- ► Integral source-drain diode
- ► High input impedance and high gain

Applications

- ► Motor controls
- ► Converters, amplifiers, and switches
- ► Power supply circuits
- ► Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

General Description

This enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Ordering Information

Part Number	Package Options	Packing
VN2460N3-G	TO-92	1000/Bag
VN2460N3-G P002	TO-92	2000/Reel
VN2460N3-G P003	TO-92	2000/Reel
VN2460N3-G P005	TO-92	2000/Reel
VN2460N3-G P013	TO-92	2000/Reel
VN2460N3-G P014	TO-92	2000/Reel
VN2460N8-G	TO-243AA (SOT-89)	2000/Reel

-G denotes a lead (Pb)-free / RoHS compliant package
Refer to 'P0xx' Tape & Reel Specs for P002, P003, P005, P013, and P014 TO-92 Taping Specifications and Winding Styles
Contact factory for Wafer / Die availablity.
Devices in Wafer / Die form are lead (Pb)-free / RoHS compliant.

Product Summary

BV_{DSS}/BV_{DGS}	$R_{DS(ON)}$ (max)	$I_{D(ON)}$ (min)
600V	20Ω	2500mA

Pin Configuration

TO-92

TO-243AA (SOT-89)
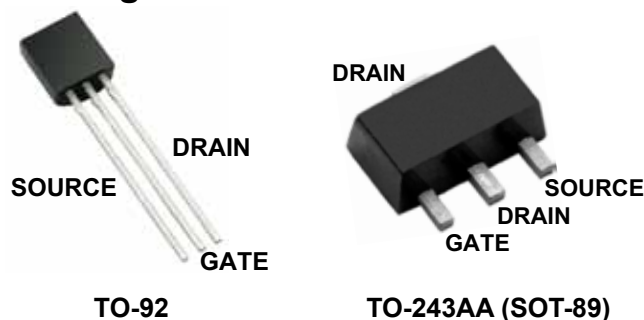
Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	BV_{DSS}
Drain-to-gate voltage	BV_{DGS}
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Product Marking

SiVN
2 4 6 0
YYWW

YY = Year Sealed
WW = Week Sealed
_____ = "Green" Packaging

Package may or may not include the following marks: Si or ⊕
TO-92

VN4FW

W = Code for week sealed
_____ = "Green" Packaging

Package may or may not include the following marks: Si or ⊕
TO-243AA (SOT-89)

Typical Thermal Resistance

Package	θ_{ja}
TO-92	132°C/W
TO-243AA (SOT-89)	133°C/W*

* Mounted on FR5 Board, 25mm x 25mm x 1.57mm

Thermal Characteristics

Package	I_D (continuous)†	I_D (pulsed)	Power Dissipation @T_A = 25°C	I_{DR}†	I_{DRM}
TO-92	160mA	500mA	1.0W	160mA	500mA
TO-243AA (SOT-89)	200mA	600mA	1.6W‡	200mA	600mA

Notes:

† I_D (continuous) is limited by max rated T_j.
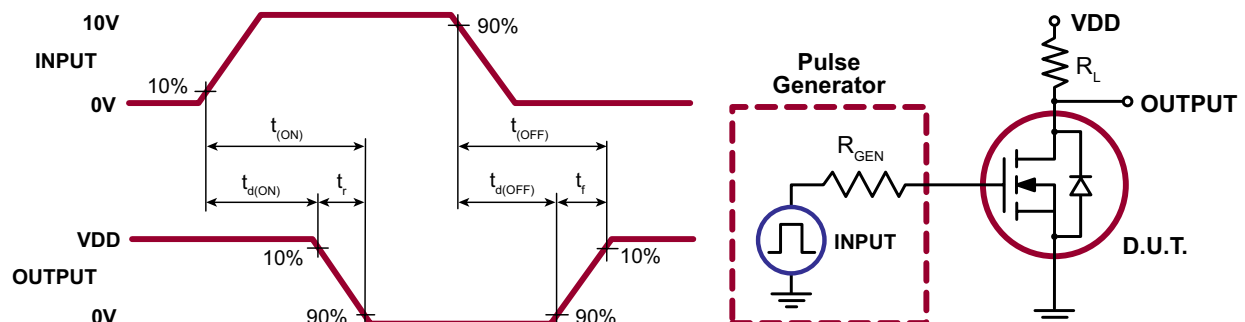
‡ Mounted on FR5 Board, 25mm x 25mm x 1.57mm.

Electrical Characteristics *(T_A = 25°C unless otherwise specified)*

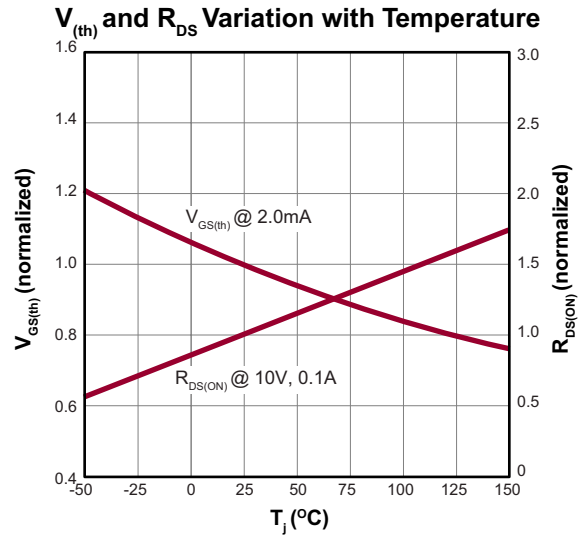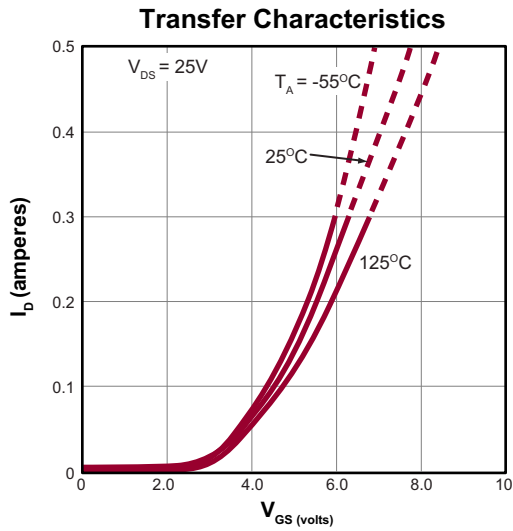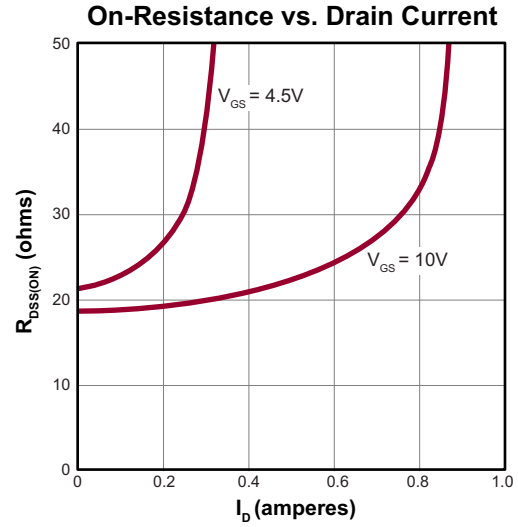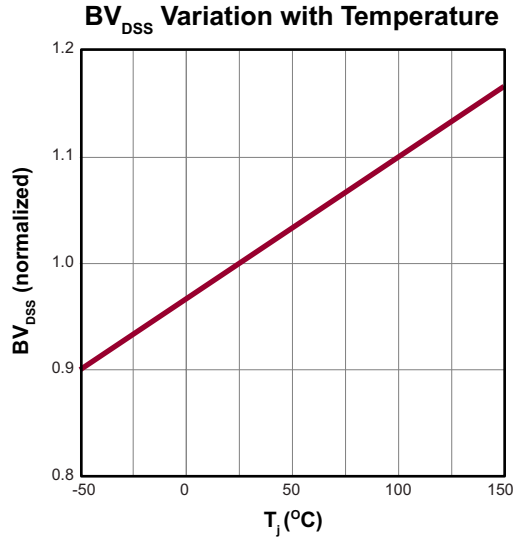| Sym	Parameter	Min	Typ	Max	Units	Conditions
BV_{DSS}	Drain-to-source breakdown voltage	600	-	-	V	V_{GS} = 0V, I_D = 2.0mA
$V_{GS(th)}$	Gate threshold voltage	1.5	-	4.0	V	V_{GS} = V_{DS}, I_D = 2.0mA
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	-5.5	mV/°C	V_{GS} = V_{DS}, I_D = 2.0mA
I_{GSS}	Gate body leakage current	-	-	100	nA	V_{GS} = ±20V, V_{DS} = 0V
I_{DSS}	Zero gate voltage drain current	-	-	10	µA	V_{GS} = 0V, V_{DS} = Max Rating
		-	-	1.0	mA	V_{DS} = 0.8 Max Rating, V_{GS} = 0V, T_A = 125°C
$I_{D(ON)}$	On-state drain current	0.25	-	-	A	V_{GS} = 10V, V_{DS} = 25V
$R_{DS(ON)}$	Static drain-to-source on-state resistance	-	-	25	Ω	V_{GS} = 4.5V, I_D = 100mA
		-	-	20		V_{GS} = 10V, I_D = 100mA
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	-	1.7	%/°C	V_{GS} = 10V, I_D = 100mA
G_{FS}	Forward transconductance	50	-	-	mmho	V_{DS} = 25V, I_D = 100mA
C_{ISS}	Input capacitance	-	-	150	pF	V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz
C_{OSS}	Common source output capacitance	-	-	50		
C_{RSS}	Reverse transfer capacitance	-	-	25		
$t_{d(ON)}$	Turn-on delay time	-	-	10	ns	V_{DD} = 25V, I_D = 250mA, R_{GEN} = 25Ω
t_r	Rise time	-	-	10		
$t_{d(OFF)}$	Turn-off delay time	-	-	25		
t_f	Fall time	-	-	20		
V_{SD}	Diode forward voltage drop	-	-	1.5	V	V_{GS} = 0V, I_{SD} = 400mA

Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
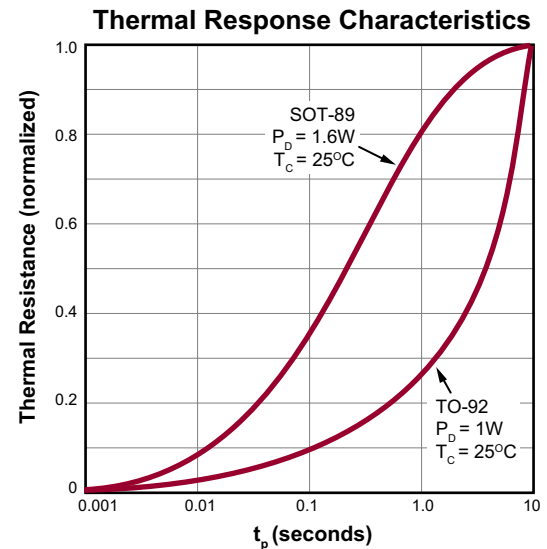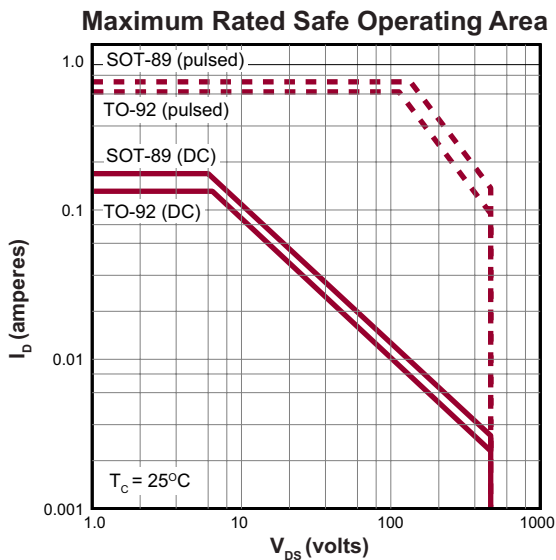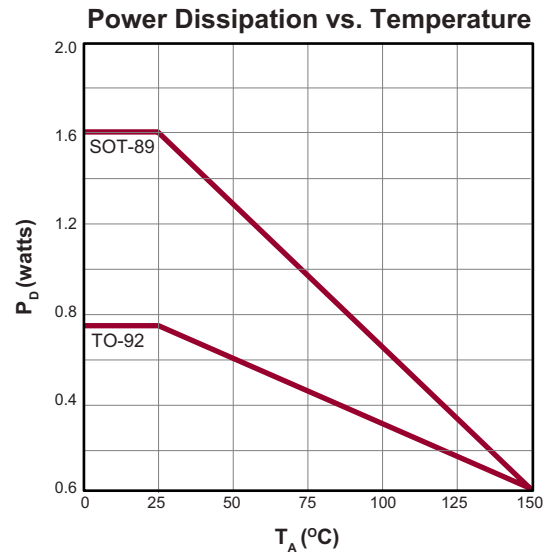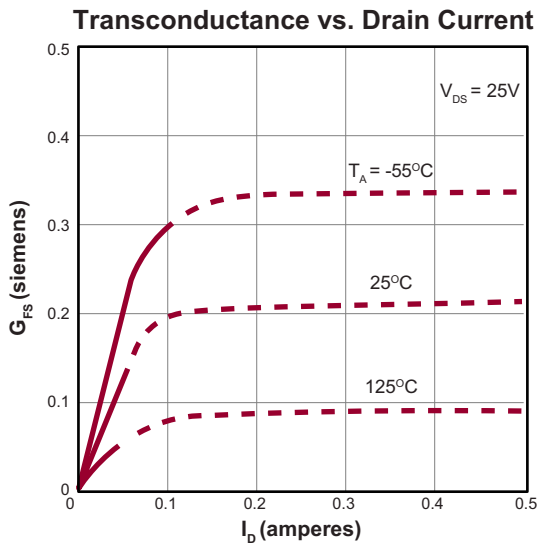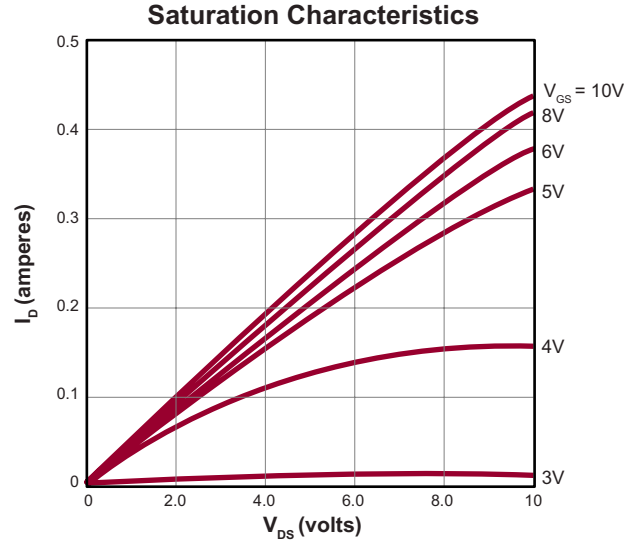2. All A.C. parameters sample tested.

Switching Waveforms and Test Circuit

Typical Performance Curves
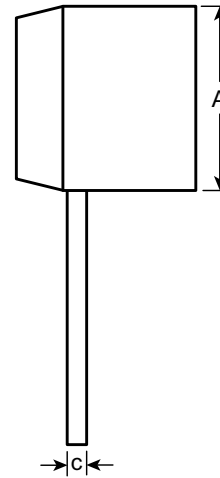
BV$_{DSS}$ Variation with Temperature

On-Resistance vs. Drain Current

Transfer Characteristics

V$_{(th)}$ and R$_{DS}$ Variation with Temperature

Capacitance vs. Drain-to-Source Voltage

Gate Drive Dynamic Characteristics

Typical Performance Curves *(cont.)*

Output Characteristics

Saturation Characteristics

Transconductance vs. Drain Current

Power Dissipation vs. Temperature

Maximum Rated Safe Operating Area

Thermal Response Characteristics

3-Lead TO-92 Package Outline (N3)

D

Seating
Plane

1 2 3

L

Front View

A

c

Side View

E1

1   3

2

E

Bottom View

e1

b

e
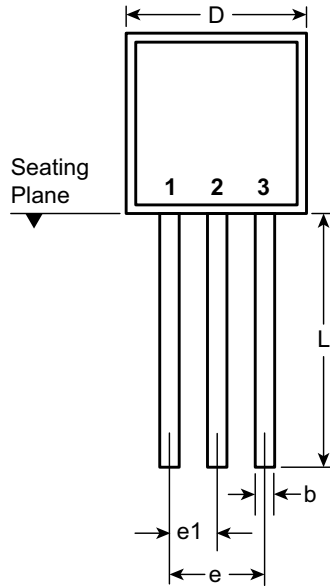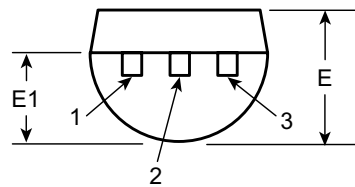
| Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014†	.014†	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022†	.022†	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.
* This dimension is not specified in the JEDEC drawing.
† This dimension differs from the JEDEC drawing.
Drawings not to scale.
Supertex Doc.#: *DSPD-3TO92N3, Version E041009.*

3-Lead TO-243AA (SOT-89) Package Outline (N8)

Top View

Side View
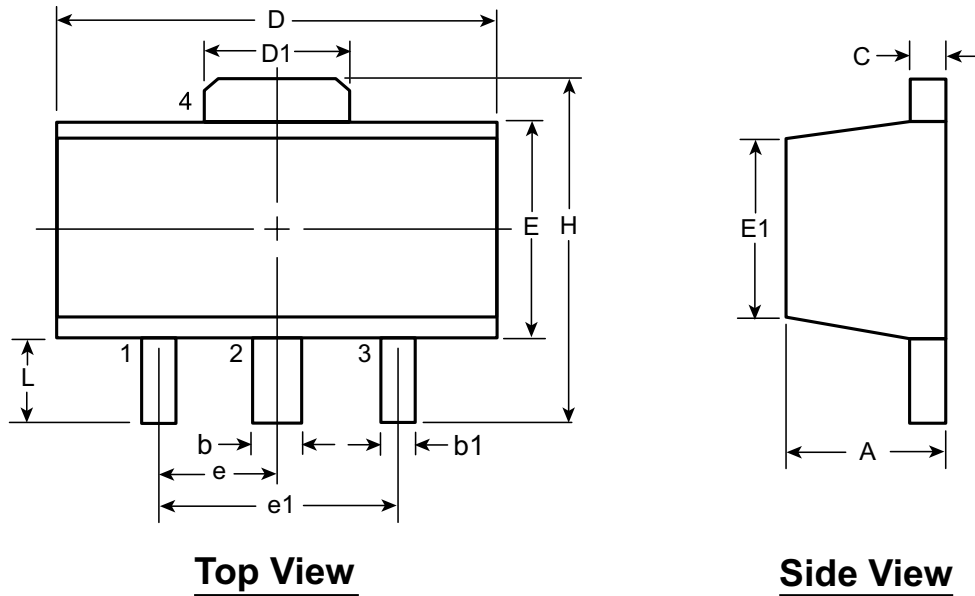
Symbol		A	b	b1	C	D	D1	E	E1	e	e1	H	L
Dimensions (mm)	MIN	1.40	0.44	0.36	0.35	4.40	1.62	2.29	2.00†	1.50 BSC	3.00 BSC	3.94	0.73†
	NOM	-	-	-	-	-	-	-	-			-	-
	MAX	1.60	0.56	0.48	0.44	4.60	1.83	2.60	2.29			4.25	1.20

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.
† This dimension differs from the JEDEC drawing
***Drawings not to scale**.*
***Supertex Doc. #:** DSPD-3TO243AAN8, Version F111010.*

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

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